

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	("20020045146").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/09/20 12:56
S2	1	10/577145	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/20 13:00
S4	14	("5517594"   "5616264"   "5661669"   "5739505"   "5895596"   "6041172"). PN. OR ("6803548"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/09/20 13:12
S3	1	(09/950876).APP.	USPAT; USOCR	OR	ON	2009/09/20 13:12
S5	4	((("20030061989") or ("20040087185") or ("20060258170") or ("20050028738")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/09/20 13:17
S6	1	("6730885").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/09/20 13:27
S7	1	("5517594").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/09/20 13:30
S10	779131	((("156/345.\$) or (118/7\$) or (315/111.\$)).CCLS. or (("216") or ("427") or ("438") or ("134") or ("204") or ("219") or ("392")).CLAS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/15 17:00
S9	11882	((("118/715) or (118/722) or (118/724) or (118/725) or (156/345.51) or (156/345.52)).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/15 17:00
S8	4842	((("118/724) or (118/725)). CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/15 17:00
S12	1425952	(control\$4 feedback feed adj back) with (thermal\$3 heat\$3 temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/15 17:01

S11	1197569	(sens\$4 measur\$5 detect\$4) with (thermal\$3 heat\$3 temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/15 17:01
S13	1245880	(load\$3 unload\$3 remov\$4 tak\$3 near2 out) with (wafer substrate object workpiece work adj piece semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/15 17:02
S14	342	S8 and S11 and (S12 same S13)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/15 17:03
S16	110	S9 and S11 and (S12 same S13) not S14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/15 17:04
S15	29423	(forecast\$3 predict\$3) with (thermal\$3 heat\$3 temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/15 17:04
S18	103	S17 not S14 not S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/15 17:05
S17	129	S10 and S11 and S15 and (S12 same S13)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/15 17:05
S19	403	(sens\$4 measur\$5 detect\$4) near5 (thermal\$3 heat\$3 temperature) and (control\$4 feedback feed adj back) near5 (thermal\$3 heat\$3 temperature) and (load\$3 unload\$3 remov\$4 tak\$3 near2 out) near5 (wafer substrate object workpiece work adj piece semiconductor)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/15 17:06
S21	40	(park near2 youngchul kawamura near2 kazuhiko wang near2 wenling).in.	US-PGPUB; USPAT	OR	ON	2009/10/15 17:07

S20	510	((sens\$4 measur\$5 detect \$4) near5 (thermal\$3 heat \$3 temperature) and (control\$4 feedback feed adj back) near5 (thermal \$3 heat\$3 temperature) and (load\$3 unload\$3 remov\$4 tak\$3 near2 out) near5 (wafer substrate object workpiece work adj piece semiconductor)). dlm.	US-PGPUB; USPAT	OR	ON	2009/10/15 17:07
S23	44	((S21 S22) and S20	US-PGPUB; USPAT	OR	ON	2009/10/15 17:09
S22	5662	(tokyo adj electron).as.	US-PGPUB; USPAT	OR	ON	2009/10/15 17:09
L12	1	w0-03041139-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/16 09:35
L13	4	((sens\$4 measur\$5 detect \$4) near5 (thermal\$3 heat \$3 temperature) and (control\$4 feedback feed adj back) near5 (thermal \$3 heat\$3 temperature) and (load\$3 unload\$3 remov\$4 tak\$3 near2 out) near5 (wafer substrate object workpiece work adj piece semiconductor) and heat\$4 near5 wall	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/16 09:47
L20	2650	(tower cassette boat) near10 (wafer substrate workpiece work adj piece object) and (heat\$4) near10 (exhaust\$3 discharg\$3 outlet)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/16 10:39
L23	134	22 and (exhaust\$3 discharg\$3 outlet) near10 (upper top ceiling roof lid)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/16 10:40
L22	243	20 and L21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/16 10:40

L21	4842	((118/724) or (118/725)). OCLS.	US-PGPUB; USPAT; USOCR; FPFS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/16 10:40
L27	2	jp-2002025997-\$.did. jp- 2002-091574-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/16 11:54
L26	0	jp-2002-025997	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/16 11:54
L28	1	("20030019585").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/10/16 14:03

10/ 16/ 09 3:37:48 PM

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